# Increased pinning strength in 2nd generation REBCO CAMBRII

## coated conductors grown by liquid assisted processes.

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#### 1. Introduction

Second generation coated conductors

- Secondary generation ReBa<sub>2</sub>Cu<sub>3</sub>O<sub>7-X</sub> (REBCO) tape has the potential to substantially improve the efficiency of hundreds of products across a variety of sectors.
- To achieve this potential new methods are needed that can improve the cost of using the tapes and increase the pinning together. Our work
- We are aiming to use liquid assisted processing (LAP) routes to grow films at an exceptionally a fast rate, thereby increasing production throughput and lowering costs.
- LAP is a PVD method where the film (here REBCO) grows from a liquid layer induced by control of the RE:Ba:Cu stoichiometry, T, pO2, etc as shown in Fig 1. The high rates of diffusion in liquids allow for very fast rates of REBCO formation [1].
- The liquid layer can either be present during deposition (in-situ LAP) or be induced after the deposition of an initial layer (ex-situ LAP).
- We have combined LAP with various techniques to create optimised pinning centre microstructures to generating films with both fast growth and strong performance.

films made using standard

PLD (see Fig 5).

#### RE:Ba:Cu ratio used Figure 1. Schematic in this study Ternary phase diagram for = In-Situ LAP study the RE-Ba-Cu system at = Ex-Situ LAP study ~ 850 °C and 10<sup>-5</sup> Torr pO<sub>2</sub> [2]. For a film to contain liquid under these 60 conditions it must have a 40 Liquid composition that lies on a 80 tie line (not shown) between the liquid and a 100/ stable phase e.g. RE<sub>2</sub>O<sub>3</sub>. **BaO**0

#### 2. In-situ Liquid Assisted Processing

a thin liquid layer to be present throughout the

deposition. The depositing flux supersaturates the liquid on contact, REBCO) to precipitate

inducing a film (here out (see Fig 2). • The biggest

## • In-situ LAP requires Deposition flux

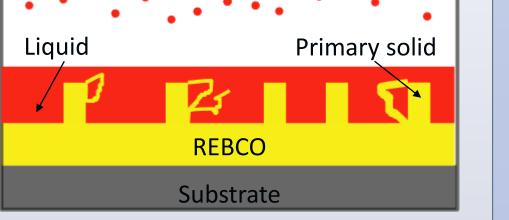
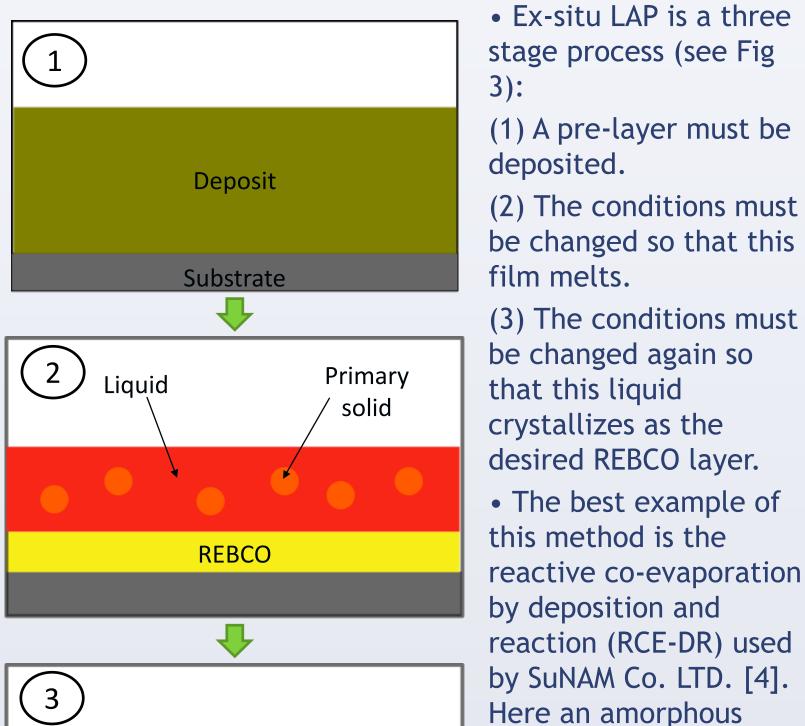


Figure 2. In-situ liquid assisted processing.

problems facing this method are stopping the liquid layer reacting with the substrate and, as the fast diffusivity leads to highly perfect REBCO crystals [3], creating strong pinning centres.

### 3. Ex-situ Liquid Assisted Processing



be changed again so that this liquid crystallizes as the desired REBCO layer. • The best example of this method is the reactive co-evaporation by deposition and reaction (RCE-DR) used by SuNAM Co. LTD. [4]. Here an amorphous pre-layer is deposited by e-beam deposition. The film is then taken through specific T and

pO<sub>2</sub> conditions (see Fig

**Figure 3.** Ex-situ liquid assisted processing. Stages 1,2 and 3 are identified in the text.

Final REBCO film

4) to transform it into REBCO via an intermediate liquid

• The main pinning centres in these REBCO films are 75-150 nm diameter Gd<sub>2</sub>O<sub>3</sub> particles. For a stronger performance, especially in high-field-low-T conditions [5][6], a better microstructure would have more, smaller,  $Gd_2O_3$  particles. • One of the biggest challenges facing this method is

generating smaller  $Gd_2O_3$  particles without sacrificing the fast growth rates.

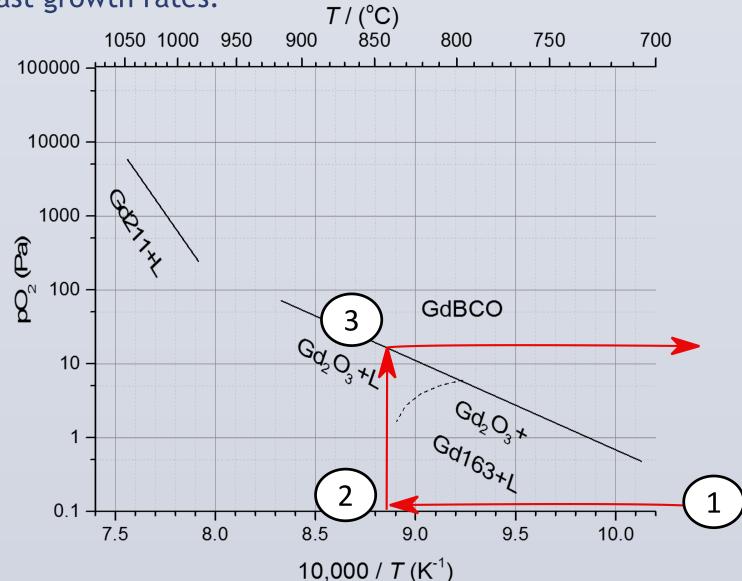
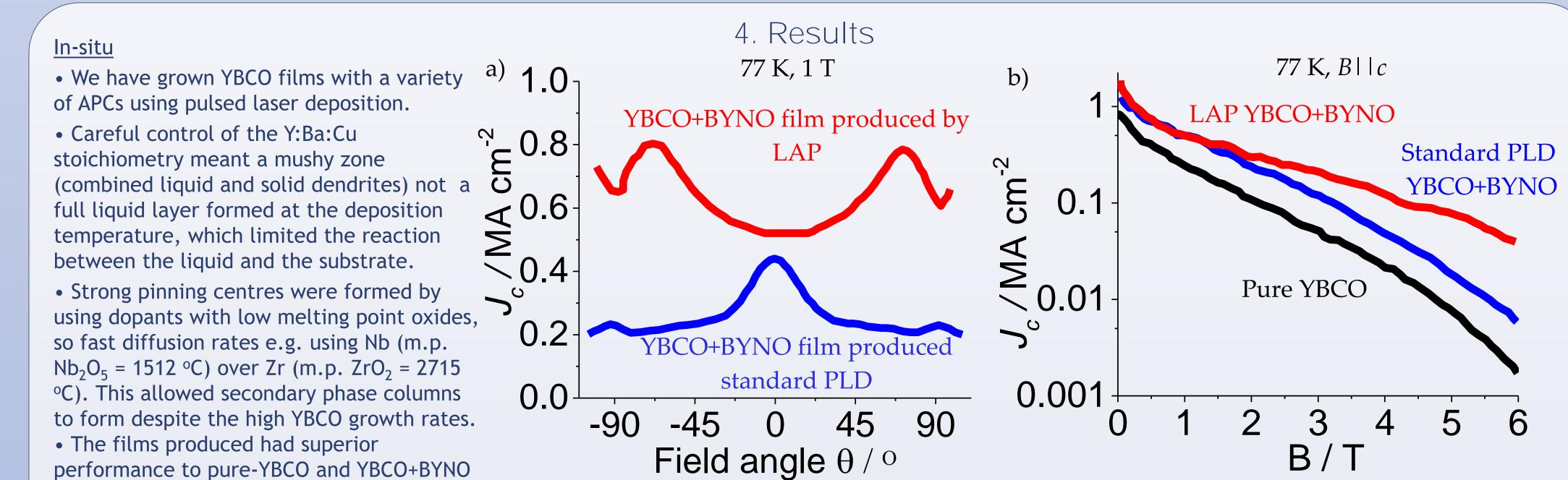


Figure 4. Stability diagram showing the RCE-DR process used by SuNAM Co. Ltd. An amorphous film (1) is processed by heating at low  $pO_2$  (2) and then raising the oxygen pressure (3) to transform the film into GdBCO and trapped Gd<sub>2</sub>O<sub>3</sub> particles via an intermediate liquid phase.

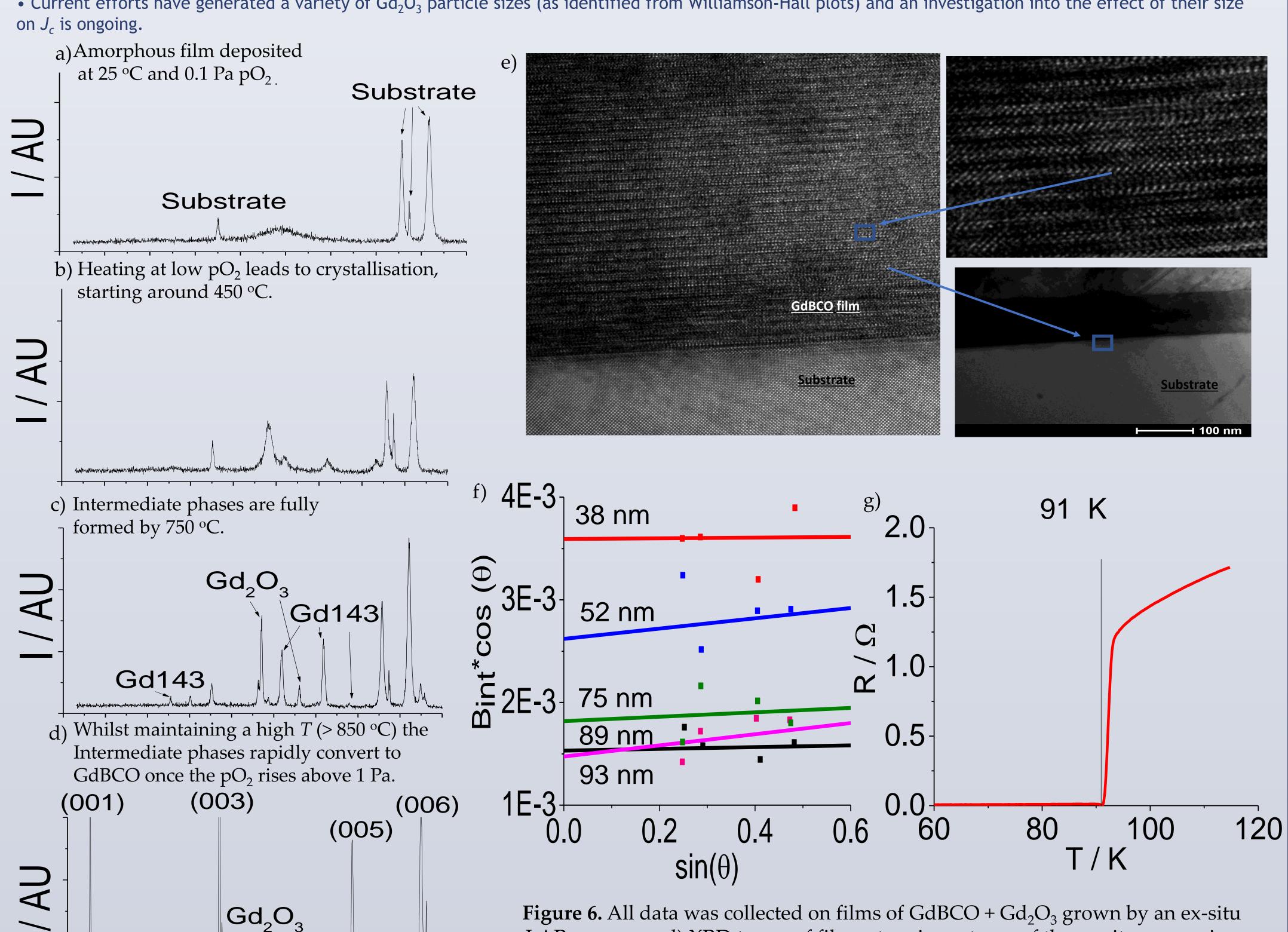


**Figure 5.** a)  $J_c$  vs angle and b)  $J_c$  vs field plots showing the strong performance of a in-situ LAP sample.

Ex-situ • We have successfully replicated the RCE-DR process using PLD, rather than e-beam deposition. 0.75-1  $\mu$ m thick GdBCO films, with strong epitaxy, high  $T_c$ 's and a dispersion of  $Gd_2O_3$  particles (see Fig 6) were produced. Importantly film formation was exceptionally fast with growth rates (> 1  $\mu$ m/min).

• Three methods are being investigated into how to refine the Gd<sub>2</sub>O<sub>3</sub> particles: 1) Using inoculants (e.g. Pt or Ce), 2) Using different rare-earths, 3) Using different Gd:Ba:Cu ratios to change the liquid:Gd<sub>2</sub>O<sub>3</sub> ratio present in the film before GdBCO crystallisation.

• Current efforts have generated a variety of Gd<sub>2</sub>O<sub>3</sub> particle sizes (as identified from Williamson-Hall plots) and an investigation into the effect of their size



**Figure 6.** All data was collected on films of GdBCO + Gd<sub>2</sub>O<sub>3</sub> grown by an ex-situ LAP process. a-d) XRD traces of films at various stages of the ex-situ processing route. e) TEM cross section showing a film with strong epitaxy, slight crystalline disorder and a remnant liquid layer on top. f) Williamson-Hall plot of 5 films with a variety of  $Gd_2O_3$  particle sizes. g) Representative R vs T plot for these films, showing their high  $T_c$  (91 K).

### 5. Conclusions

To realise the dream of widespread coated conductor new methodologies are needed to produce tapes both fast and with high performance. Our study looks into trying to achieve this using both in-situ and ex-situ methods of liquid assisted processing, whilst simultaneously looking at ways to control and even design the microstructures to optimise their pinning characteristics. We have successfully created highly aligned high  $T_c$  films, at high rates, and with good  $J_c$  performance relative to standard PLD films.

#### Acknowledgements

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